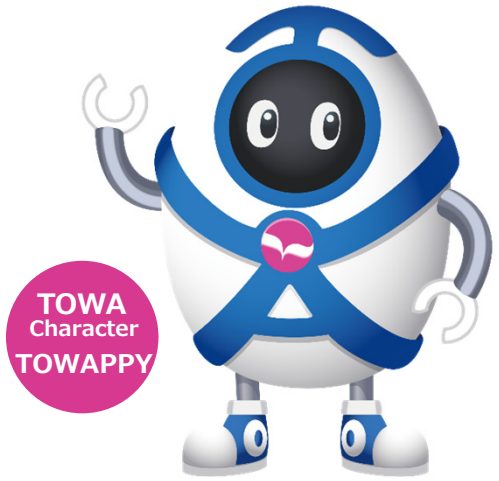

1st Quarter - FY2024 Business Results

August 8, 2024

TOWA CORPORATION

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FY2024 1st Quarter Summary

(100M¥)

Orders	Net Sales	Operating Profit	Ordinary Profit	Net Profit
130.7	132.5	22.1	24.2	16.9

- **Orders and net sales of our original compression equipment and molds remained at high levels.**

  Orders and net sales of our original compression equipment and molds, for generative AI related product and device for communication, continue to remain high levels.

- **Net sales and profits at each stage are all increased, YoY.**

  Capital expenditure in Korea and China continues to remain steady. Investment in Taiwan is gradually beginning to recover and net sales of molding equipment and molds have increased. Additionally, the utilization rates of our customers have improved, leading to an increase in net sales of Total Solution Service (TSS). As a result, profits at each stage showed substantial improvement, YoY.

FY2024 1st Quarter Consolidated Financial Results

(100M¥)

	FY2023 1Q Results	FY2024 1Q Results	Variance	YoY
Net Sales	95.1	132.5	+ 37.4	+ 39.3%
Operating Profit	9.2	22.1	+ 12.9	+ 140.3%
Ordinary Profit	11.3	24.2	+ 12.8	+ 112.5%
Net Profit	7.8	16.9	+ 9.0	+ 115.9%

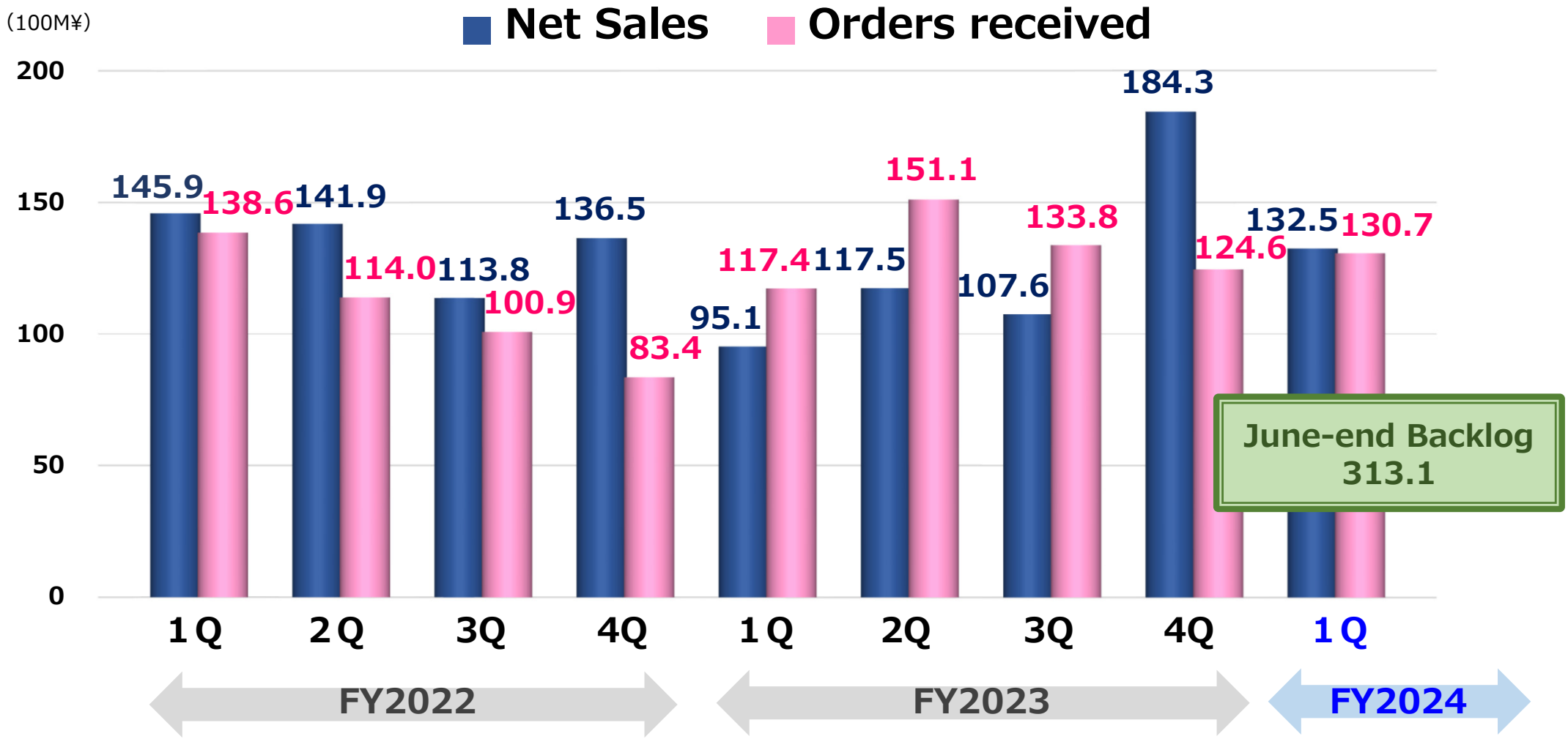
※Net Profit= Profit attributable to owners of parent

FY2024 1st Quarter Net Sales by Business Segment

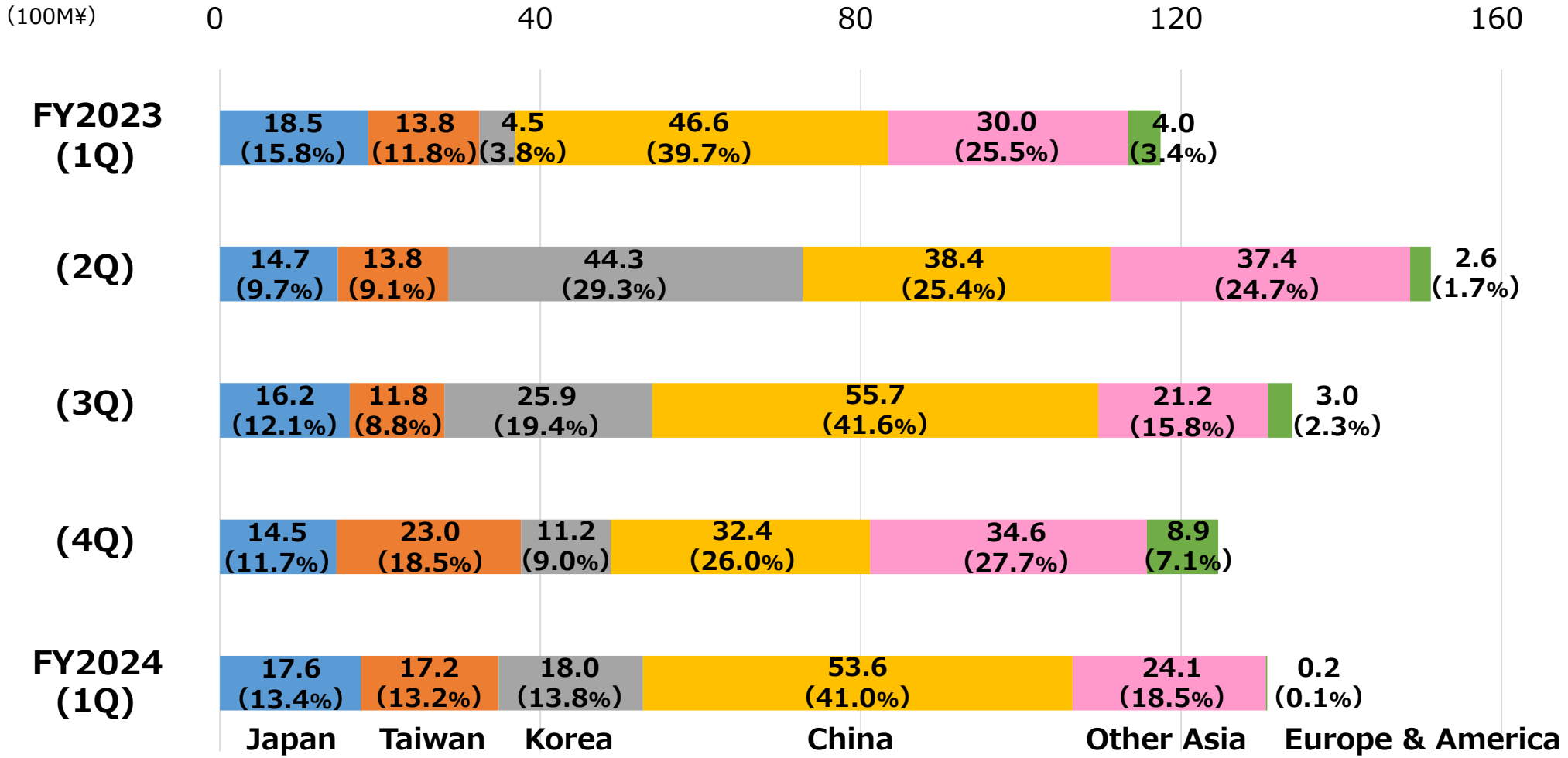
(100M¥)

	FY2023 1Q Results	FY2024 1Q Results	Variance	YoY
Net Sales	95.1	132.5	+ 37.4	+ 39.3%
Semiconductor	71.0	100.6	+ 29.6	+ 41.7%
Fine Plastic	5.5	5.7	+ 0.2	+ 3.8%
New Business	14.4	22.0	+ 7.6	+ 52.8%
Laser Processing Machine	4.2	4.2	▲ 0.0	▲ 0.2%

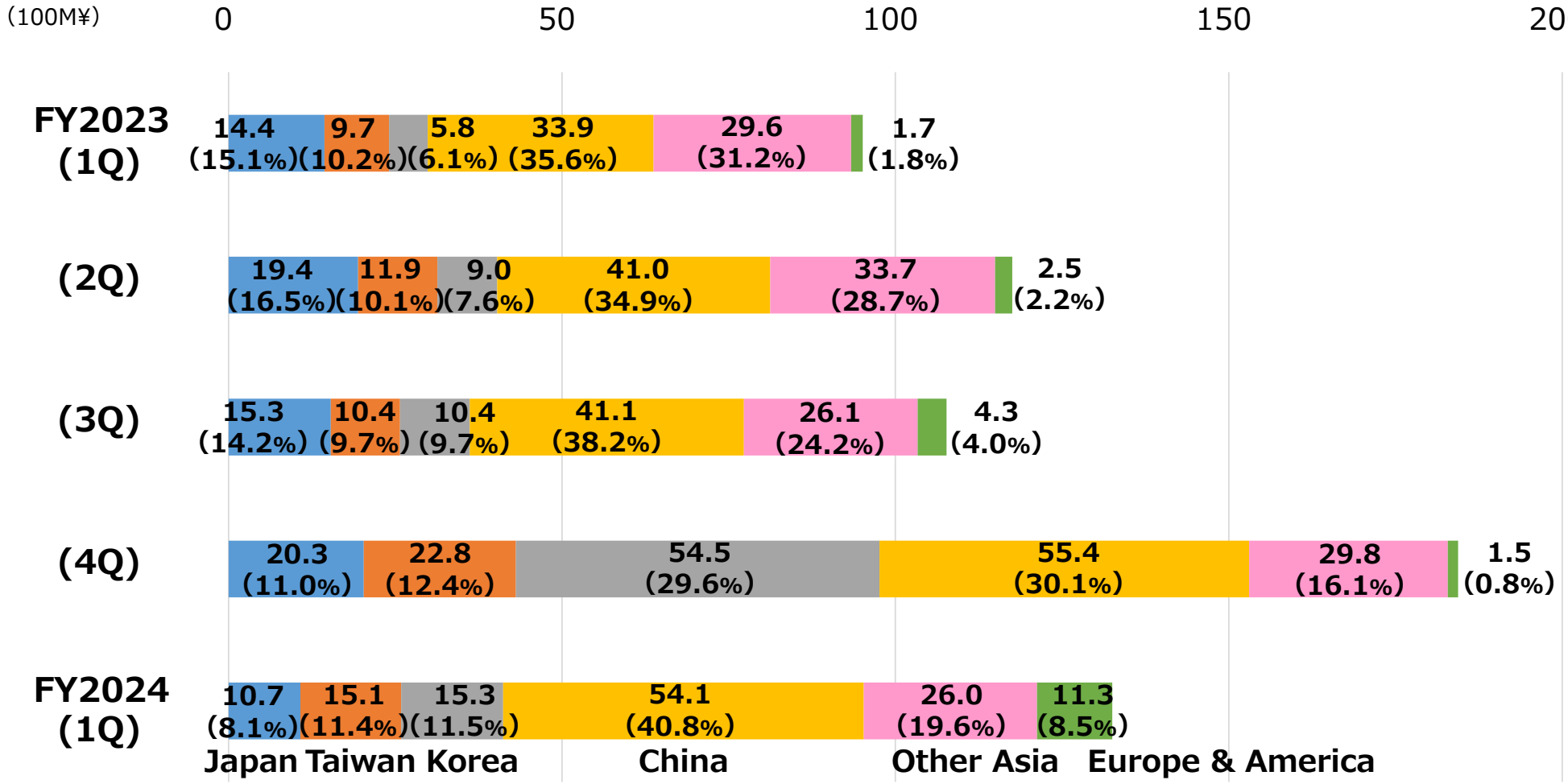
Net Sales and Orders Trend



Trend of Orders Distribution Ratio by Geographic Area (Place of destination)

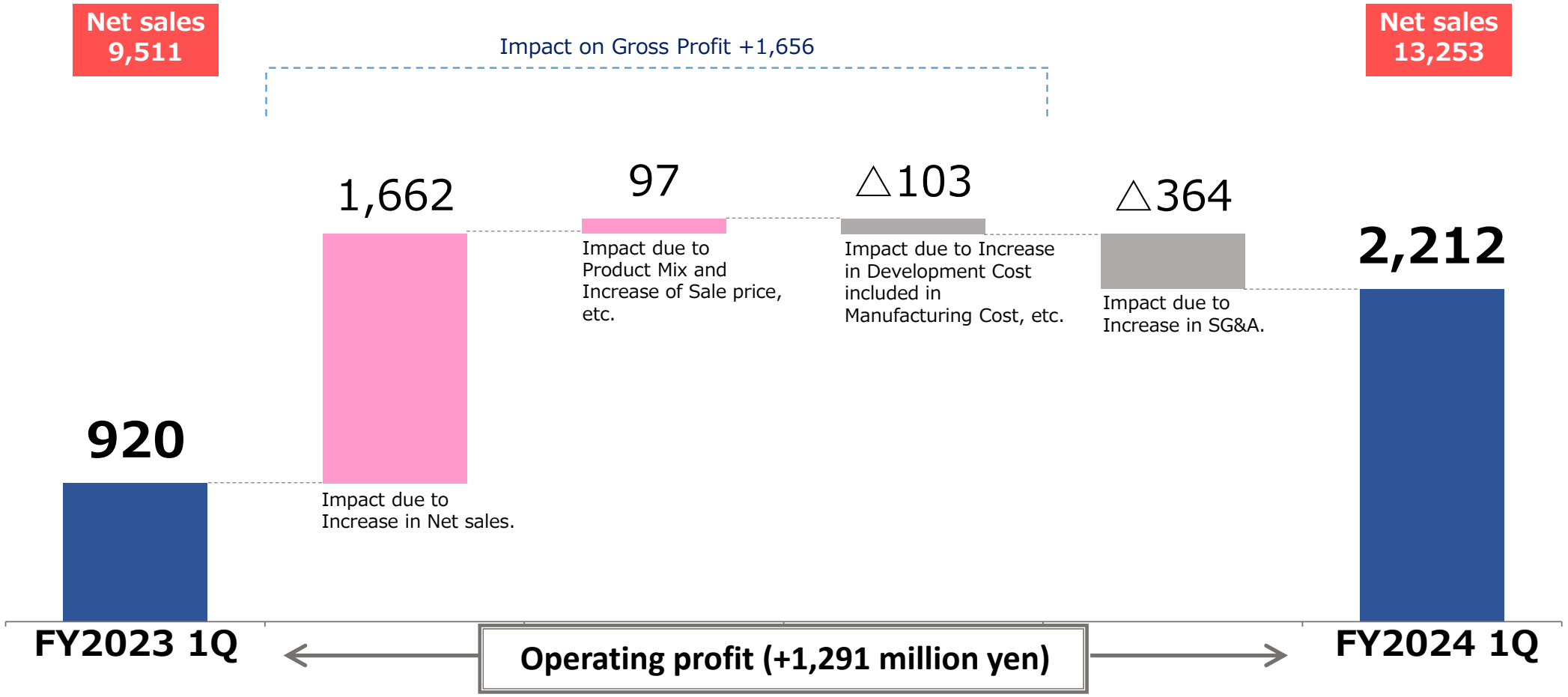


Trend of Sales Distribution Ratio by Geographic Area (Place of destination)



FY2024 1Q Operating Profit Variance Analysis（YoY）

（100M¥）



※Yen amounts are rounded down to millions.

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FY2024 Forecast of Consolidated Financial Results

※Initial estimate is unchanged.

(100M¥)

	FY2023 Results	FY2024 Forecast			Variance	YoY
		1H	2H	FY		
Net Sales	504.7	287.0	313.0	600.0	+ 95.2	+ 18.9%
Operating Profit	86.6	56.5	69.5	126.0	+ 39.3	+ 45.5%
Operating Margin	17.2%	19.7%	22.2%	21.0%	–	+ 3.8pt
Ordinary Profit	90.7	56.5	69.5	126.0	+ 35.2	+ 38.8%
Net Profit	64.4	39.6	48.7	88.3	+ 23.8	+ 37.0%

※Net Profit= Profit attributable to owners of parent

FY2024 Forecast of Consolidated Financial Results by business segment

※Initial estimate is unchanged.

(100M¥)

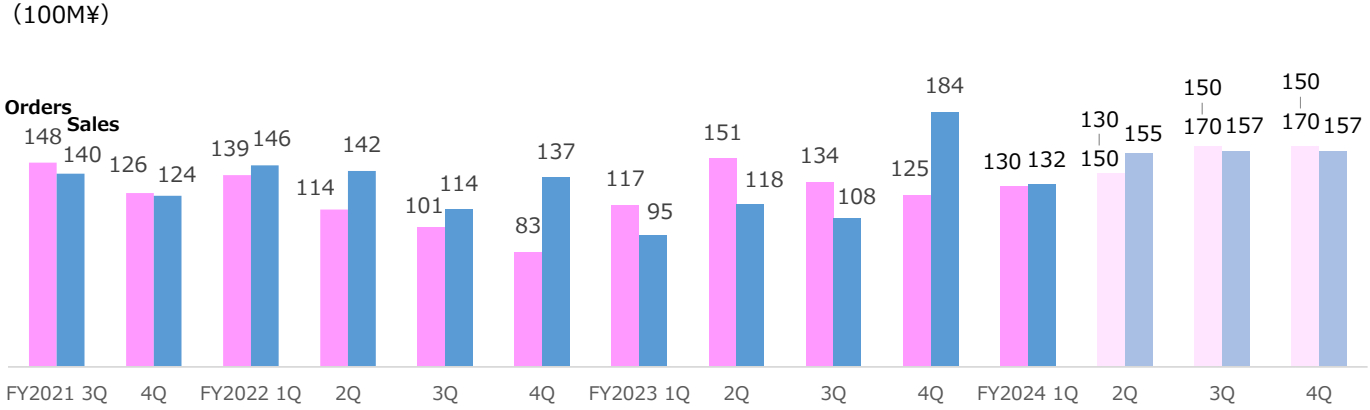
	FY2023 Results	FY2024 Forecast			Variance	YoY
		1H	2H	FY		
Net Sales	504.7	287.0	313.0	600.0	+ 95.2	+ 18.9%
Semiconductor	383.2	213.0	230.0	443.0	+ 59.8	+ 15.6%
Fine Plastic	21.5	11.0	11.0	22.0	+ 0.5	+ 2.3%
New Business	75.8	50.0	54.0	104.0	+ 28.2	+ 37.2%
Laser Processing Machine	24.2	13.0	18.0	31.0	+ 6.8	+ 28.3%

Market Outlook

Market Outlook of this Fiscal Year

- Generative AI-related investment and active investment in China are expected to continue driving the market from the second quarter onward.
- An inventory adjustment are progressing, and the utilization rate of OSAT is showing an improving trend. Capital expenditure is also expected to gradually recover from the second quarter to the second half of this year, and we anticipate an increase in our company's net sales starting from the second quarter.

Orders/Sales Forecast



(100M¥)

Orders Forecast

2Q
130-150

3Q
150-170

4Q
150-170

Profit & Loss Forecast

Net Sales	600.0
Operating Profit	126.0
Ordinary Profit	126.0
Net Profit	88.3

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Next-Generation Semiconductor Packaging Consortium Participation

The US-JOINT Participation established by RESONAC

We are strengthening our collaboration in developing packages using our compression equipment for next-generation semiconductor such as generative AI and autonomous driving with North American semiconductor manufacturers, fabless companies, and major IT companies.

ULVAC RESONAC Azimuth TOWA Packaging Open Innovation in Silicon Valley US-JOINT KLA tok Kulicke & Soffa NAMICS MLI MOSES LAKE INDUSTRIES IMEC

Compression Equipment for WLP
Model : CPM1080

Name	US-JOINT（JOINT : Jisso Open Innovation Network of Tops)
Objective	Creation of next-generation semiconductor packaging evaluation platforms and development of packaging technology in the United States
Location	Union City, California, United States

Winner of the “Semiconductor of the Year” Grand Prix

The 30th Semiconductor of the Year 2024
TOWA wins the Grand Prix
on Semiconductor Manufacturing Equipment category

Optimal molding equipment for manufacturing semiconductor for generative AI

Molding Equipment for Chiplet product
Model : YPM1250-EPQ

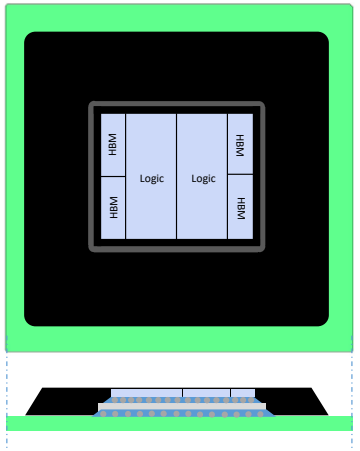


Image of
Chiplet product

TOWA Vision 2032

「To the top of the world with change」

《Contact》
TOWA CORPORATION Corporate Planning Dept.
5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto 601-8105
Telephone number : 075-692-0251

This presentation material contains TOWA Group's forward-looking statements regarding, including but not limited to, plans, policies, finances, technologies, products, services and results. Such forward-looking statements are the judgements made by the Group based on available data, assumptions and applicable methods etc. as of the presentation date, and contain various risks and uncertainties. Also, new risks and uncertainties can occur anytime and it is impossible to predict the occurrence and the effect of them. Thus, please understand the actual results could considerably differ from the forward-looking statements.

Appendix

Corporate Overview

Company name	TOWA CORPORATION
Products	Semiconductor/LED Manufacturing Equipment, Ultra-Precision Molds, Fine Plastic Products, Laser Processing Machines
Established	April 1979
President & CEO	Hirokazu Okada
Number of Employees	2,047 (consolidated) [as of June 2024]
Paid in capital	8.9 billion yen
Code Number	6315
Address	5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto

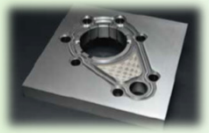
TOWA's Business

New Business

- TSS
  (Total Solution Service)
- Tools for precision process
- Fine process
- Coating

Remodeling, repair, Prevention & Upkeep

Fine process technology



Undertake processing

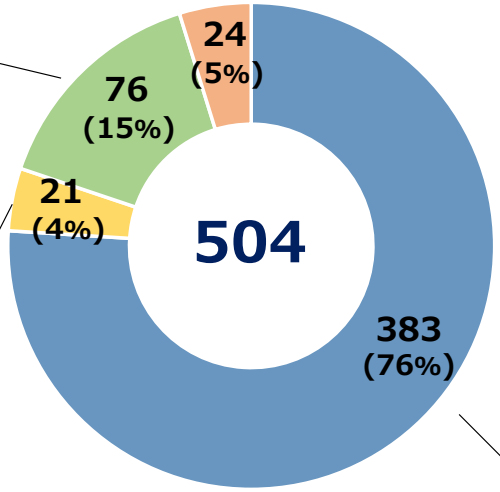
Tool（end mill）

Fine Plastic

- Fine plastic products
- Medical products

Parts of drip

Component for syringe



Net Sales (100M¥)
(FY2023)

Laser Processing Machines

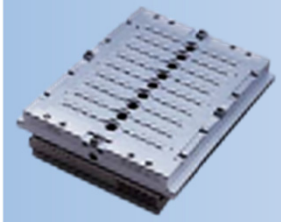
- Laser Trimmer
- Wafer Marker
- Laser Welder

Laser Trimmer
SL432R

Wafer Marker
SL473GS3

Semiconductor Manufacturing (SM) Equipment

- Precision molds for SM
- Molding equipment for SM
- Singulation equipment for SM



Transfer Mold

Molding Equipment
Model PMC 2030-D

Molding Equipment
Model CPM 1080

Factories

● TOWA Corporation ● Affiliated Companies

Korea

● **TOWA KOREA Co., Ltd.**
Equipment, precision mold and component manufacturing

● **TOWA FINE Co., Ltd.**
Blade

China

● **TOWA (Suzhou) Co., Ltd.**
Equipment and precision mold manufacturing

● **TOWA (Nantong) Co., Ltd.**
Equipment and precision mold manufacturing

Malaysia

● **TOWAM Sdn. Bhd.**
Equipment manufacturing

● **TOWA TOOL Sdn. Bhd.**
Mold manufacturing

Kyoto

● **Headquarters/Factory (Kyoto-shi)**
Equipment and precision mold development and manufacturing

Kyoto

● **Kyoto East Plant (Ujitawara-cho)**
Mold manufacturing

Saga（Tosu-shi）

● **Kyushu Work**
Mold manufacturing

Yamanashi（Nirasaki-shi）

● **BANDICK Corporation**
Fine plastic products manufacturing

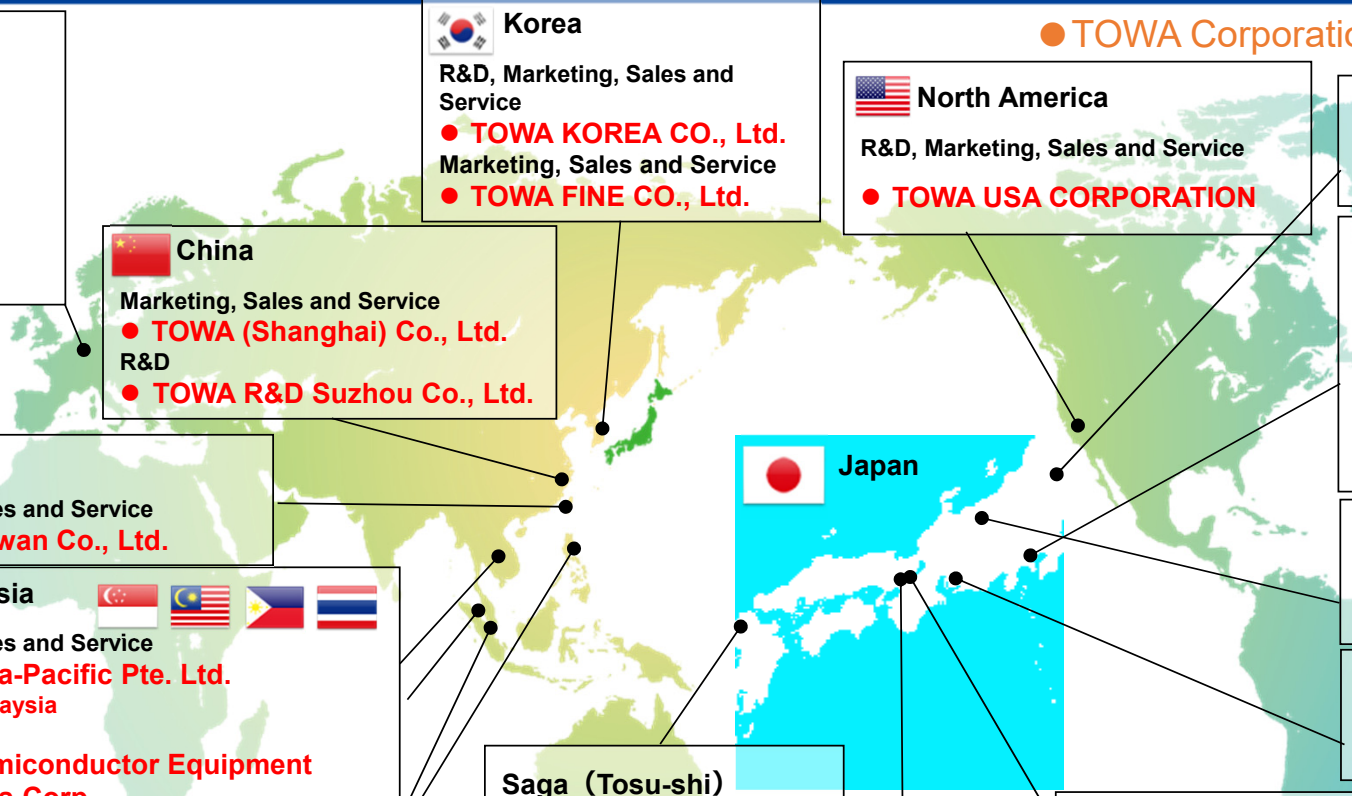
Kanagawa（Sagamihara-shi）

● **TOWA LASERFRONT Corp.**
Laser & Laser Processing machines development and manufacturing

Japan

Sales/Service facility

● TOWA Corporation ● Affiliated Companies



Netherlands
R&D, Marketing, Sales and Service
● TOWA Europe B.V.

Germany
Marketing, Sales and Service
● TOWA Europe GmbH

Korea
R&D, Marketing, Sales and Service
● TOWA KOREA CO., Ltd.
Marketing, Sales and Service
● TOWA FINE CO., Ltd.

China
Marketing, Sales and Service
● TOWA (Shanghai) Co., Ltd.
R&D
● TOWA R&D Suzhou Co., Ltd.

Taiwan
Marketing, Sales and Service
● TOWA Taiwan Co., Ltd.

Southeast Asia
Marketing, Sales and Service
● TOWA Asia-Pacific Pte. Ltd.
Singapore, Malaysia
● TOWA Semiconductor Equipment Philippines Corp.
Philippines
● TOWA THAI COMPANY LIMITED
Thailand
● TOWA TOOL Sdn. Bhd.
Malaysia

North America
R&D, Marketing, Sales and Service
● TOWA USA CORPORATION

Japan

Saga（Tosu-shi）
Service
● TOWATEC Co., Ltd.

Osaka
Sales and Service
● TOWA LASERFRONT Corp.

Kyoto
Marketing and Sales
● Headquarters/Factory (Kyoto-shi)
● Kyoto East Plant (Ujitawara-cho)
Service
● TOWATEC Co., Ltd.（Kyoto-shi）

Miyagi（Tomiya-shi）
Service
● TOWATEC Co., Ltd.

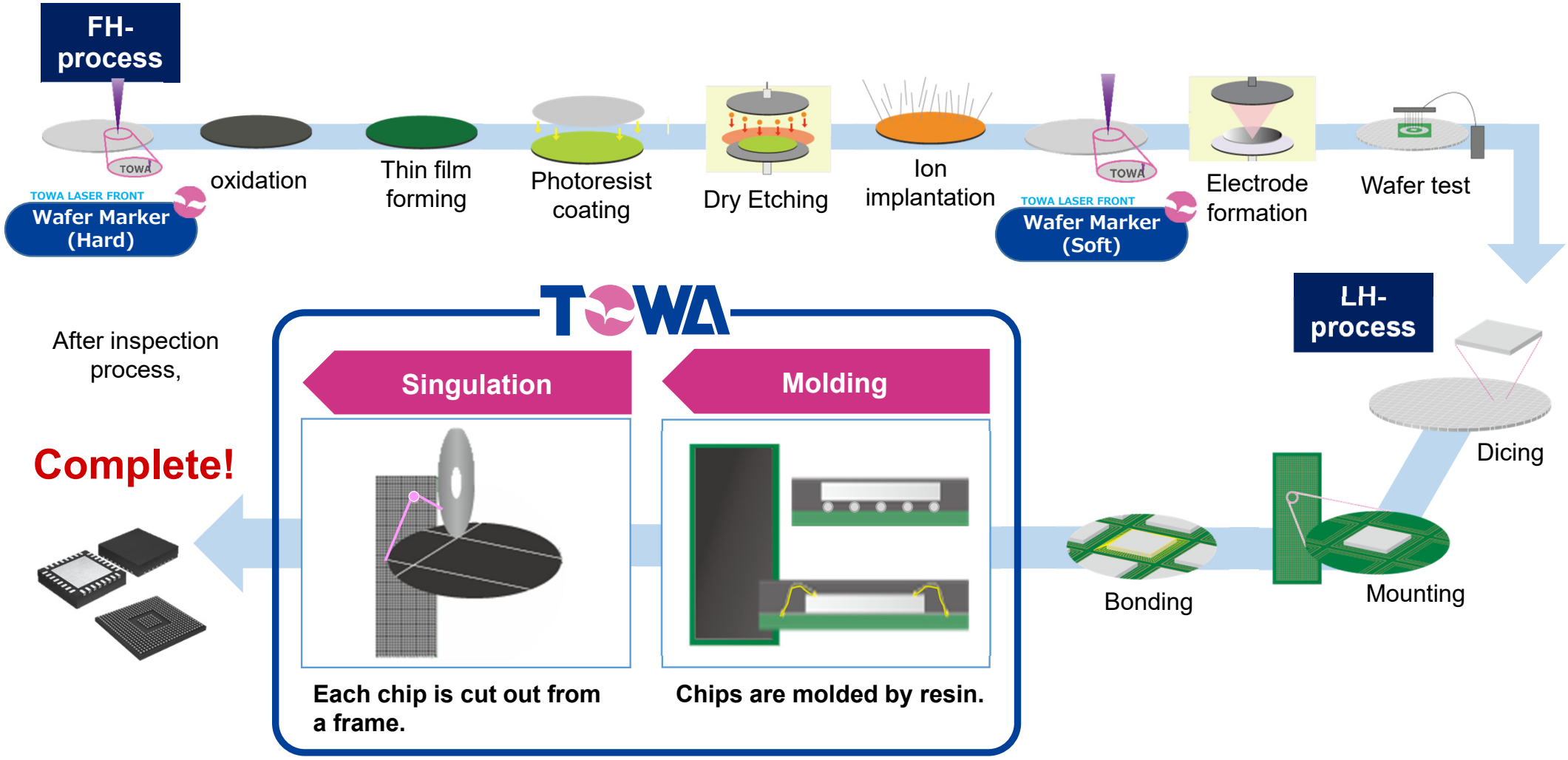
Tokyo (Chiyoda-ku)
Marketing, Sales
● Tokyo Sales Office

Kanagawa（Sagamihara-shi）
R&D, Marketing, Sales and Service
● TOWA LASERFRONT Corp.

Nagano（Nagano-shi）
Marketing, Sales
● Nagano Sales Office

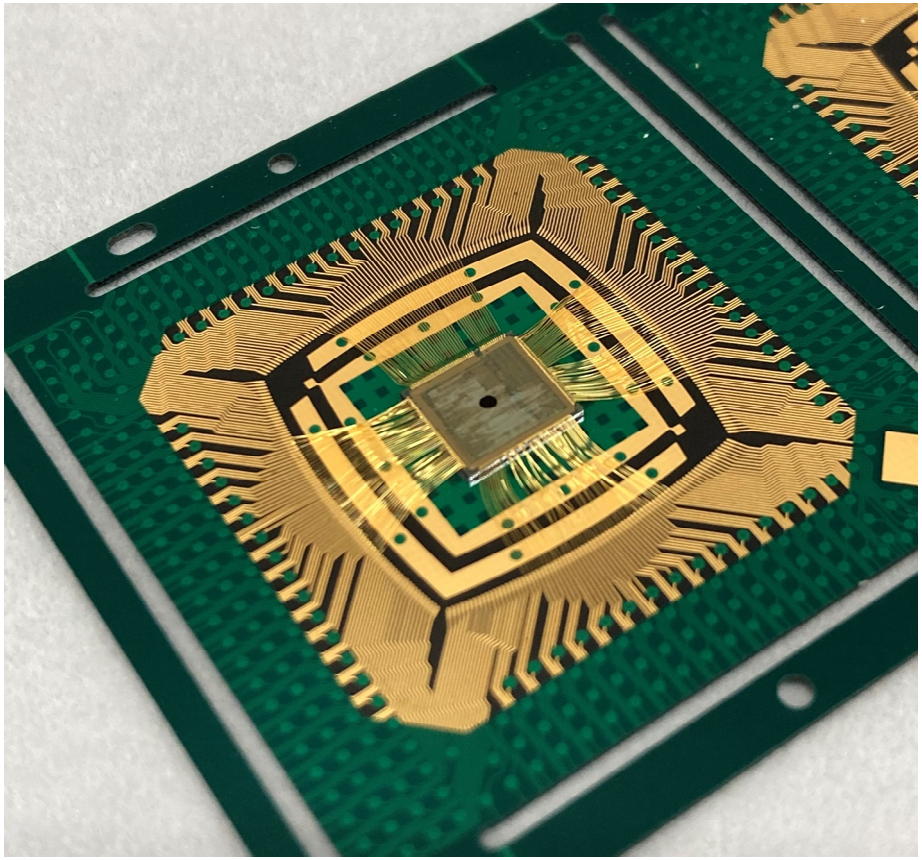
Aichi（Nagoya-shi）
Sales and Service
● TOWA LASERFRONT Corp.

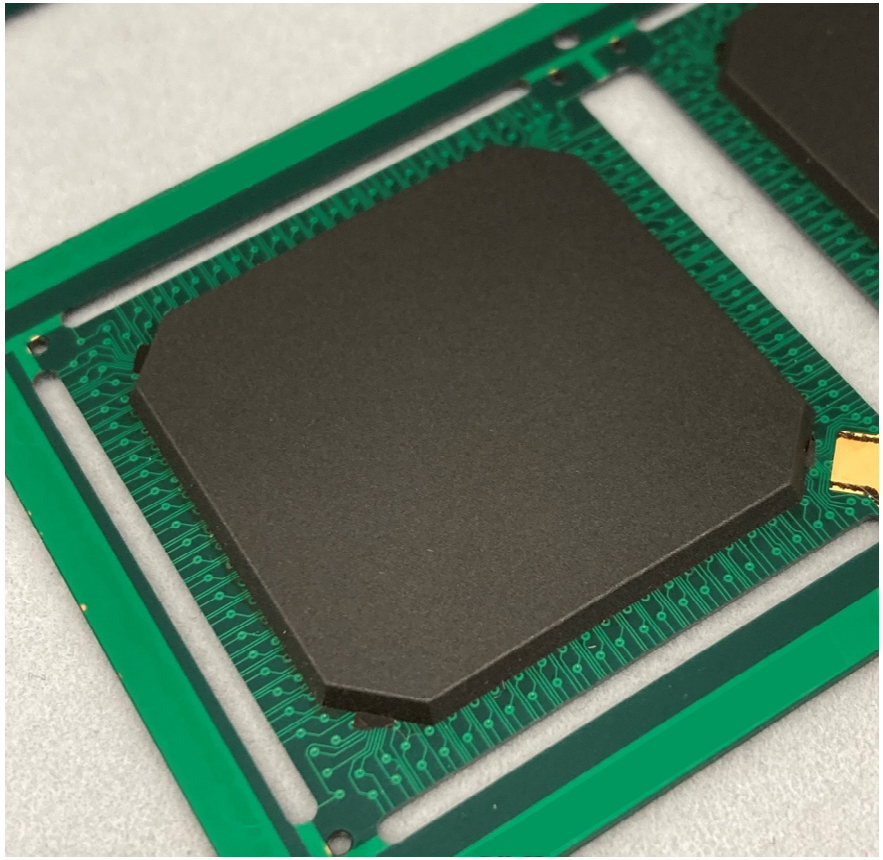
Semiconductor Manufacturing



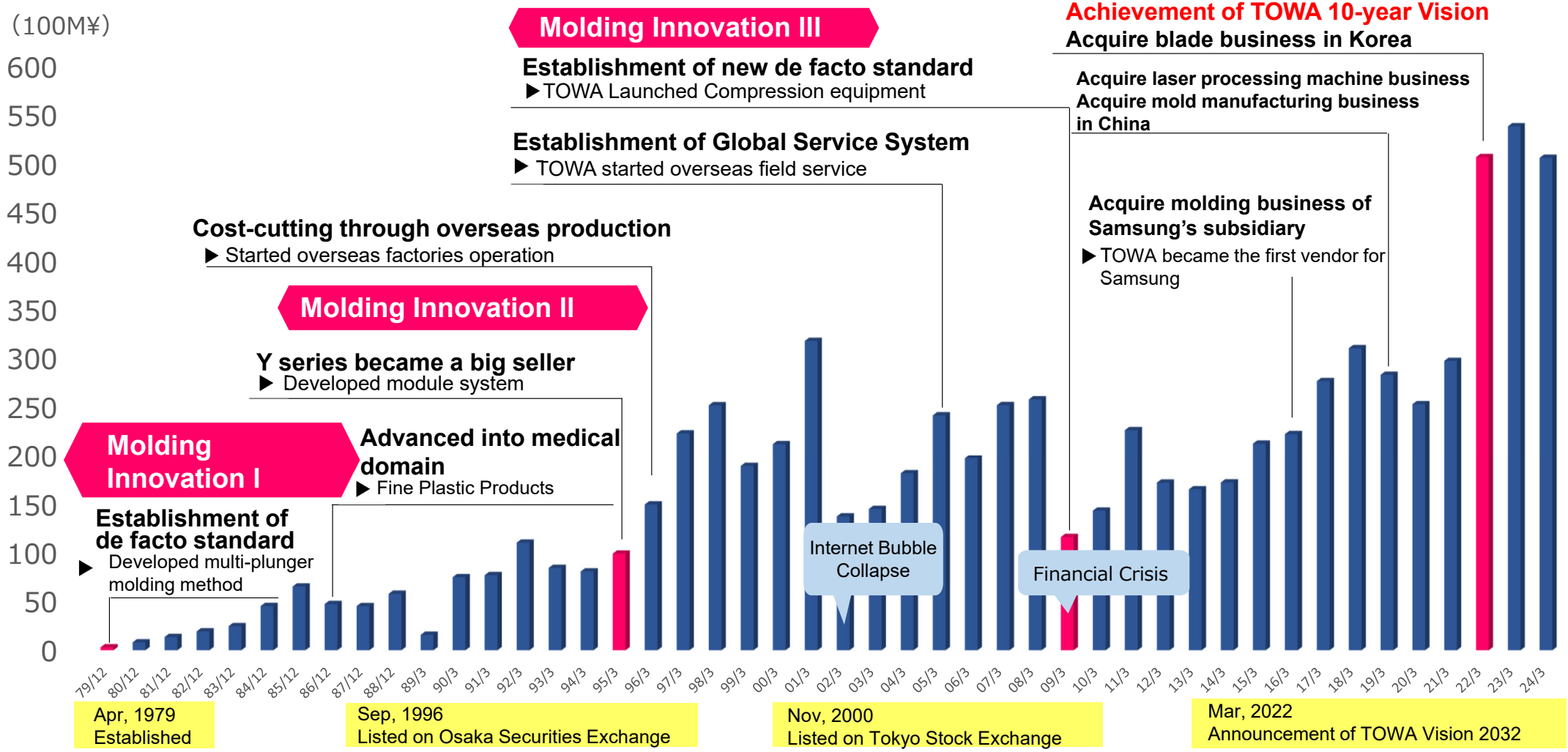
Molding

Chips and Wire are molded by resin.





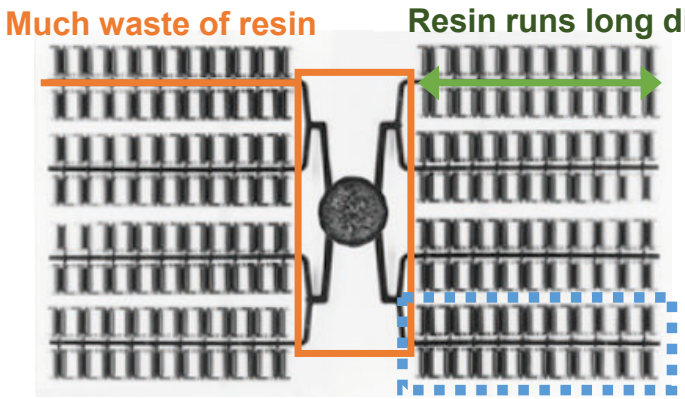
Progress of TOWA

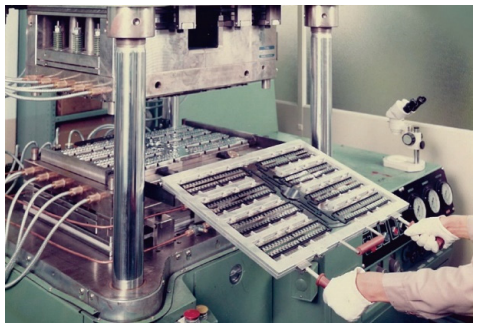


Molding innovation I （1979）

Conventional Mold

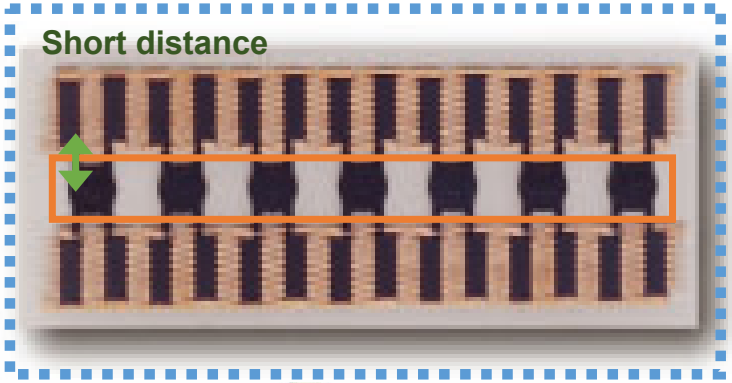
Manual molding by putting one palm size resin into the central pod. Resin runs long distance. Molding quality is not homogeneous. And much waste of resin.





Multi-Plunger Mold

Auto molding by putting finger size resins into several pods. This realized short runner, homogeneous molding quality and less waste of resin.



Molding innovation II（1995）

Module System (Y series)

Before the development of Module System, Molding equipment was・・・

Each equipment is designed depends on what or how much it will manufacture.
Semiconductor manufacturers had to buy another equipment ,
when they want to manufacture another type of product or increase their product volume.

2 Module Connection

Module System enables to adjust press number!!

・Even you have only one Y series machine,
you can manufacture many types of products or increase your product volume.

Y series is sufficient to meet the needs of assembly subcontractor, to perform backend process bringing from IDM.

4 Module Connection

Semiconductor molding equipment is one of the strongest quality of TOWA.

Molding innovation III（2009）

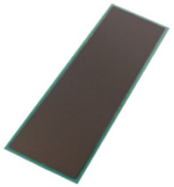
Compression Molding Equipment

Independent compression molding technology has enabled to mold cutting-edge devices, and cut the cost significantly!!
The compression technology is unrivaled from its launch in 2009 because of the patent and technical difficulty.

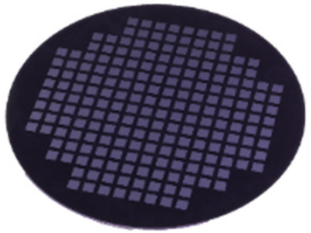
Compression Equipment
Model PMC 2030-D

Features

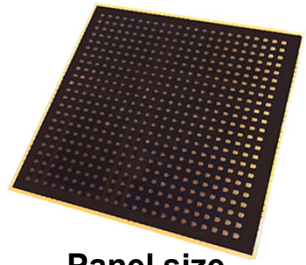
- 100% resin efficiency
  (CO2 emissions reduced by about 70%)
- Compression molding with no resin fluidity
  (reduce defective products)
- Most suitable for cutting-edge such as memory and 5G
- Applicable to both granular type and liquid type resin
- Applicable to both panel size and wafer size



Substrate size
100×300mm



Wafer size
φ300mm



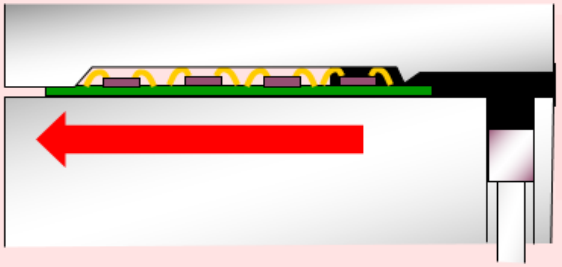
Panel size
600mm×600mm

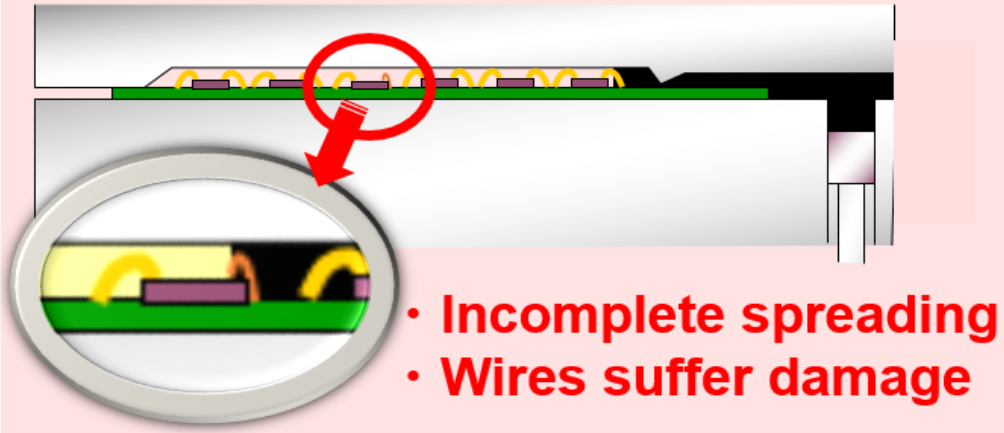
Encapsulation（Molding）Process

Transfer molding

Injecting resin type

Resin flows

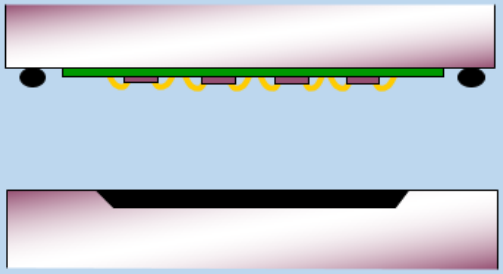




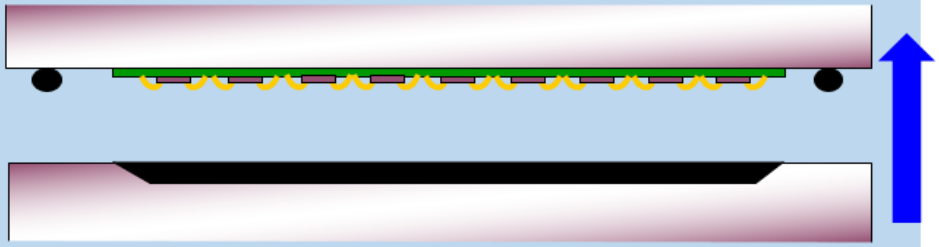
- Incomplete spreading
- Wires suffer damage

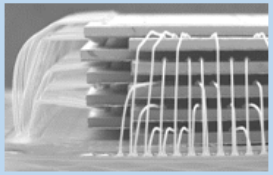
Compression molding

Compressing resin type



No Resin fluidity





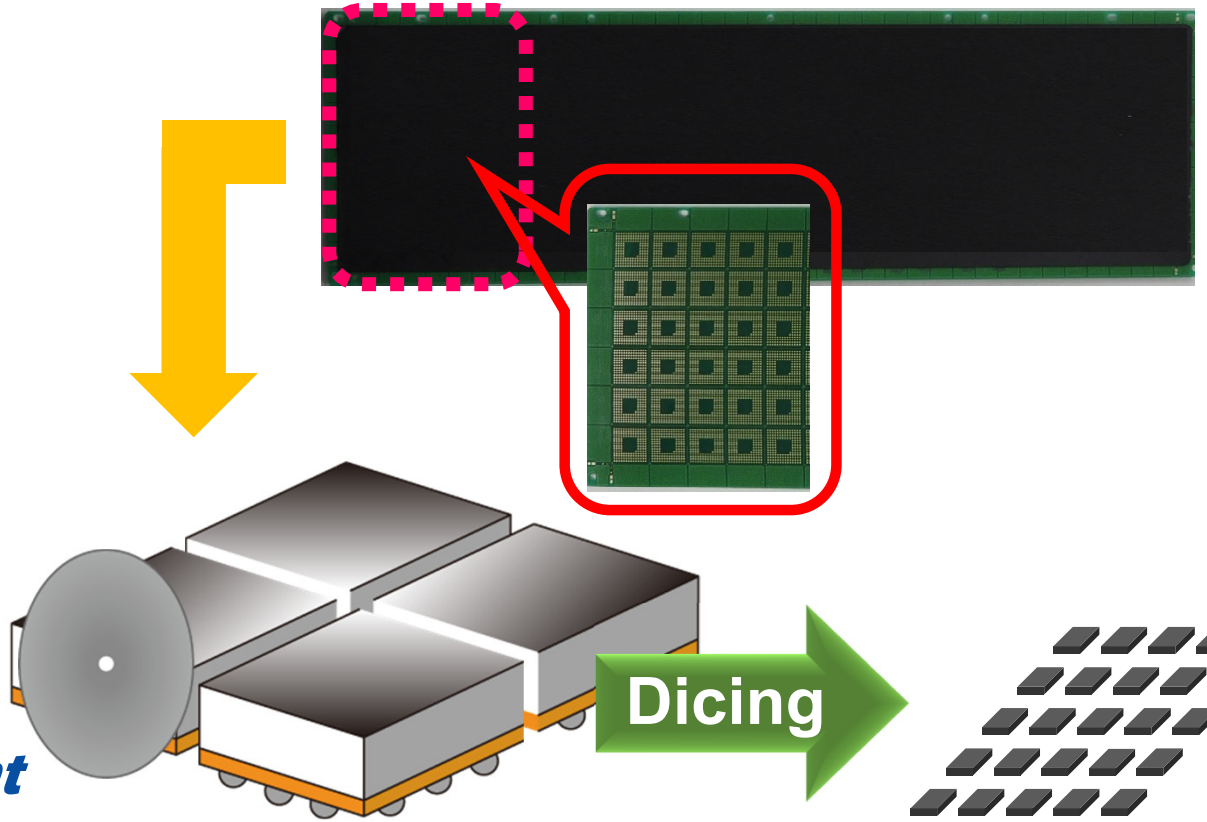
- TOWA enabled large size panel molding
- No damage to products

Singulation Process

Smallest !
Realized 1.0×1.0mm
Size dicing

Singulation Equipment
Model FMS 4040

After molding, frames are cut to each semiconductor chip



Semiconductor Manufacturing Equipment Line-Up

～Compression Mold～

Compression Equipment
Model CPM 1180

Work max size：625x620mm

Compression Equipment
Model CPM 1080

Work max size：φ300mm、320x320mm

Compression Equipment
Model PMC 2030-D

Work max size：100x300mm

～ Transfer Mold～

Transfer Equipment
Model YPM 1180

Work max size：100x300mm

～ Singulation～

Singulation Equipment
Model FMS 4040

Work max size：100x300mm